PRODUCT SPECIFICATION

CDTECH Model: **S019RQ02HN**

CUSTOMER Model: -

Description: **1.9” TFT-LCD Module**

Version: **1.0**

CDTECH	PREPARED BY	CHECKED BY	APPROVED BY
SIGNATURE			
DATE	2023.3.16	2023.3.16	2023.3.16

	SIGNATURE	DATE
CUSTOMER APPROVAL		

Record of Revisions

Version	Revise Date	Description	Page
1.0	2023-3-16	First Release	-

Contents

1. General Specifications

1.1 LCM General Information

Item	Specification	Unit
LCD Size	1.9	inch
Number of Pixels	170 (H) RGB x 320 (V)	pixels
Display Mode	Normally Black	-
Viewing Direction	Free	o' clock
Interface	MCU/RGB/SPI	-
Display Colors	262K	colors
Outline Dimension	25.80 (H) x 49.72 (V) x 1.36 (D)	mm
Active Area	22.70 (H) x 42.72 (V)	mm
Pixel Pitch	0.1335 (H) x 0.1335 (V)	mm
Driver IC	ST7789T3	-
Operation Temperature	-20~70	℃
Storage Temperature	-30~80	℃

Note1:Requirements on environmental protection RoHS compliant.

2. Absolute Maximum Ratings

Item	Symbol	MIN.	MAX.	Unit	Note
Analog Supply voltage	VDD	-0.3	5.0	V	Note 1
Digital supply voltage	IOVCC	-0.3	3.6	V	Note 1

Note 1:Permanent damage may occur to the LCD module if beyond this specification.
Functional operation should be restricted to the conditions described under normal operating conditions.

3. Elecrical Characteristics

3.1 Recommended Operating Condition for TFT LCD

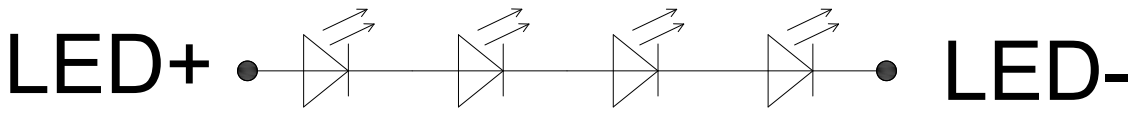
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Analog Supply voltage	VDD	2.5	2.8	3.3	V	
Analog supply current	I_{VDD}	-	TBD	-	mA	VDD=2.8V
Logic supply voltage	IOVCC	1.65	1.8	3.3	V	
Logic supply current	I_{IOVCC}	-	TBD	-	mA	IOVCC=1.8V
Logic input voltage	VIH	0.7*IOVCC	-	IOVCC	V	
	VIL	GND	-	0.3*IOVCC	V	

3.2 Recommended Driving Condition for Backlight

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Driving Current	I_F	-	20	-	mA	
Driving Voltage	V_F	10.8	-	13.2	V	
Power consumption	W_{BL}	0.216	-	0.264	W	
LED Life-Time	N/A	-	30,000	-	Hours	Ta=25℃ Note 1

Note 1:LED lifetime is defined as the module brightness decay 50% of original brightness at Ta=25 degree, typical current.

Note 2:LED circuit :



4. Interface Pin Assignment

4.1 LCM Pin Assignment

Recommended connector：TF31-40S-0.5SH manufactured by HIROSE

No.	Symbol	Description
1	VCI	Power supply
2	IOVCC	Power supply
3	IMO	Select the interface mode (Note 1)
4	IM3	Select the interface mode (Note 1)
5	IM2	Select the interface mode (Note 1)
6	IM1	Select the interface mode (Note 1)
7	RESET	Global reset pin
8	VSYNC	Vertical sync input. Negative polarity
9	HSYNS	Horizontal sync input. Negative polarity
10	DOTCLK	Dot-clock signal and oscillator source
11	ENABLE	Display enable pin for controller
12-29	DB17-DB0	Data bus
30	SDO	Serial data output
31	SDI	Serial data input
32	RD	Serve as a read signal
33	WR/SCK	WRX pin, serves as a write signal
34	RS	Data/Command Selection pin, Low: Command H: Parameter
35	CS	Chip select pin
36	GND	Ground
37	LEDA	Power for LED backlight (Anode)
38	LEDK	Power for LED backlight (Cathode)
39	LEDK	Power for LED backlight (Cathode)
40	GND	Ground

Note 1:The MCU II Interface mode select
IM3 is tied high in module for MCU II Mode
IM2 is tied low in module for MCU II Mode

<table>
<tr><th>Name</th><th>I/O</th><th>Description</th><th>Connect Pin</th></tr>
<tr><td>IM3, IM2,
IM1, IM0</td><td>I</td><td>-The MCU interface mode select.
<table>
<tr><th>IM3</th><th>IM2</th><th>IM1</th><th>IM0</th><th>MPU Interface Mode</th><th>Data pin</th></tr>
<tr><td>0</td><td>0</td><td>0</td><td>0</td><td>80-8bit parallel I/F</td><td>DB[7:0]</td></tr>
<tr><td>0</td><td>0</td><td>0</td><td>1</td><td>80-16bit parallel I/F</td><td>DB[15:0]</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>0</td><td>80-9bit parallel I/F</td><td>DB[8:0]</td></tr>
<tr><td>0</td><td>0</td><td>1</td><td>1</td><td>80-18bit parallel I/F</td><td>DB[17:0],</td></tr>
<tr><td rowspan="2">0</td><td rowspan="2">1</td><td rowspan="2">0</td><td rowspan="2">1</td><td>3-line 9bit serial I/F</td><td>SDA: in/out</td></tr>
<tr><td>2 data lane serial I/F</td><td>SDA: in/out
WRX: in</td></tr>
<tr><td>0</td><td>1</td><td>1</td><td>0</td><td>4-line 8bit serial I/F</td><td>SDA: in/out</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>0</td><td>80-16bit parallel I/F II</td><td>DB[17:10],
DB[8:1]</td></tr>
<tr><td>1</td><td>0</td><td>0</td><td>1</td><td>80-8bit parallel I/F II</td><td>DB[17:10]</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>0</td><td>80-18bit parallel I/F II</td><td>DB[17:0],</td></tr>
<tr><td>1</td><td>0</td><td>1</td><td>1</td><td>80-9bit parallel I/F II</td><td>DB[17:9]</td></tr>
<tr><td>1</td><td>1</td><td>0</td><td>1</td><td>3-line 9bit serial I/F II</td><td>SDA: in/
SDO: out</td></tr>
<tr><td>1</td><td>1</td><td>1</td><td>0</td><td>4-line 8bit serial I/F II</td><td>SDA:in/
SDO: out</td></tr>
</table></td><td>DGND/VDDI</td></tr>
</table>

5. Interface Characteristics

5.1 Serial Interface Characteristics (4-line serial):

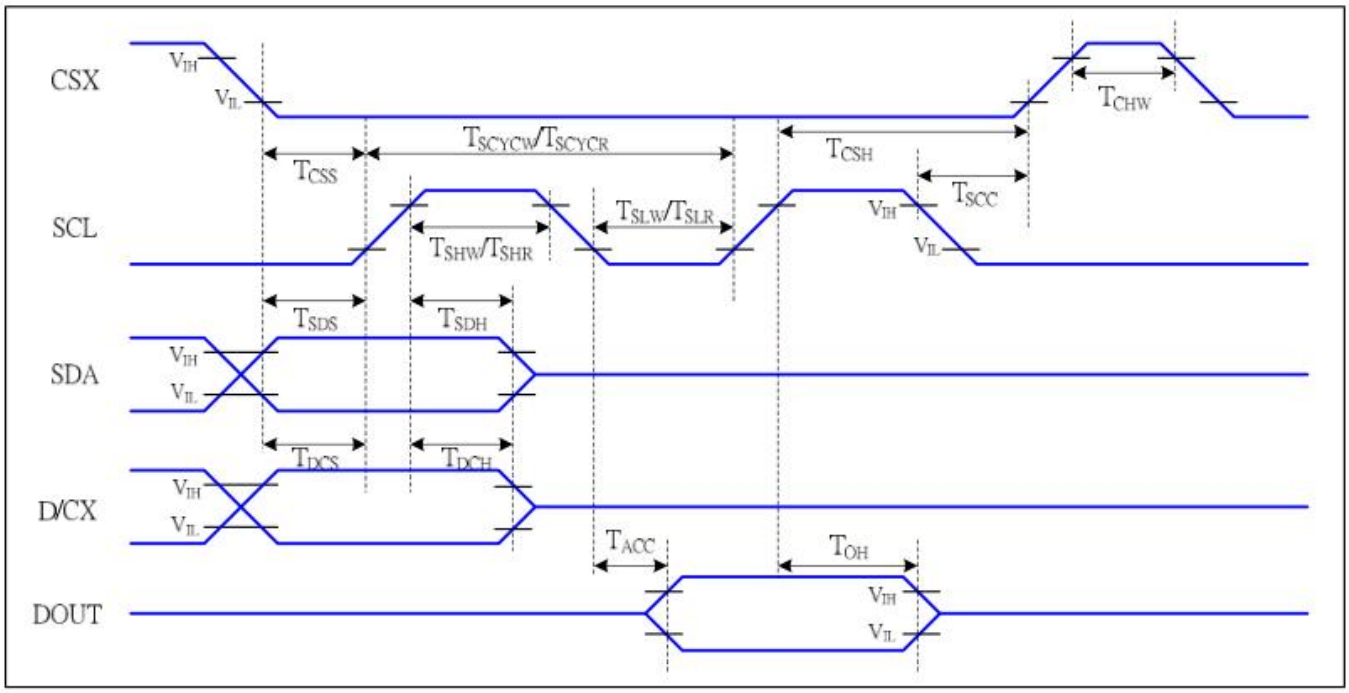


Figure 5 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	16		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 6 4-line serial Interface Characteristics

5.2 Serial Interface Characteristics (3-line serial):

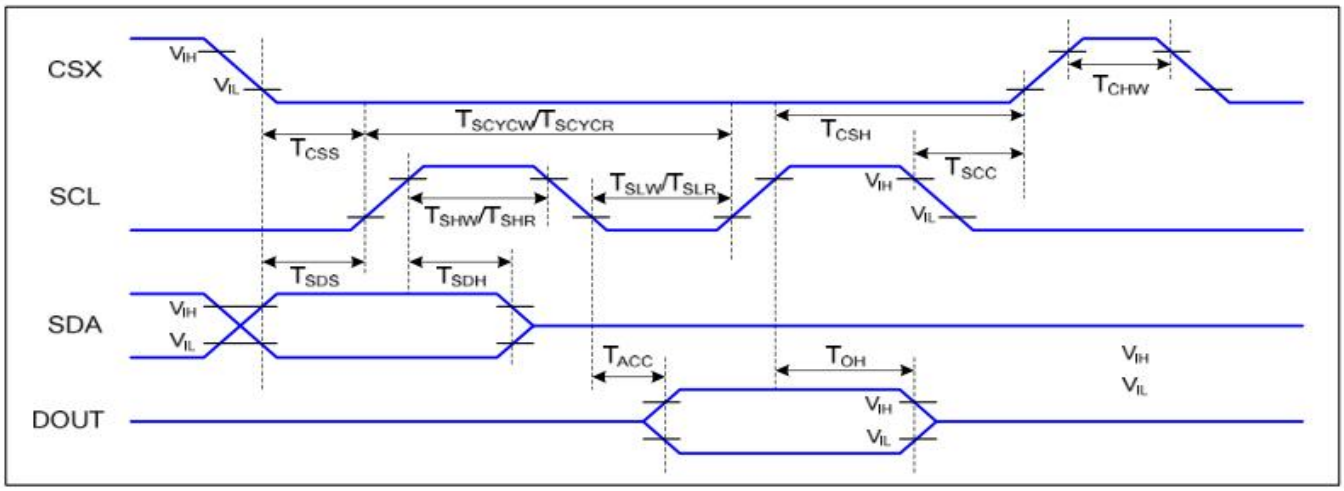


Figure 4 3-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	16		ns	
	T_{SHW}	SCL "H" pulse width (Write)	7		ns	
	T_{SLW}	SCL "L" pulse width (Write)	7		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	7		ns	
	T_{SDH}	Data hold time	7		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 5 3-line serial Interface Characteristics

5.3 RGB Interface Characteristics:

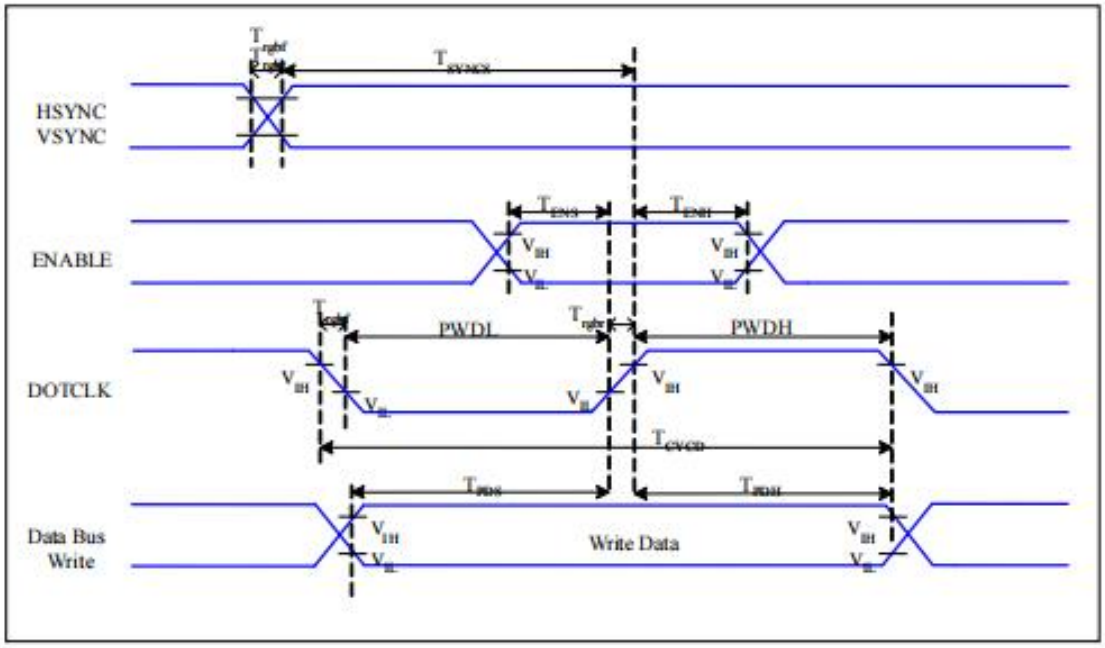


Figure 6 RGB Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	25	-	ns	
	T_{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T_{PDS}	PD Data Setup Time	50	-	ns	
	T_{PDH}	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	35	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	35	-	ns	

	T_{ENH}	Enable Hold Time	35	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	35	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	35	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	80	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	10	ns	
DB	T_{PDS}	PD Data Setup Time	35	-	ns	
	T_{PDH}	PD Data Hold Time	35	-	ns	

Table 8 6 Bits RGB Interface Timing Characteristics

5.4 Reset Timing:

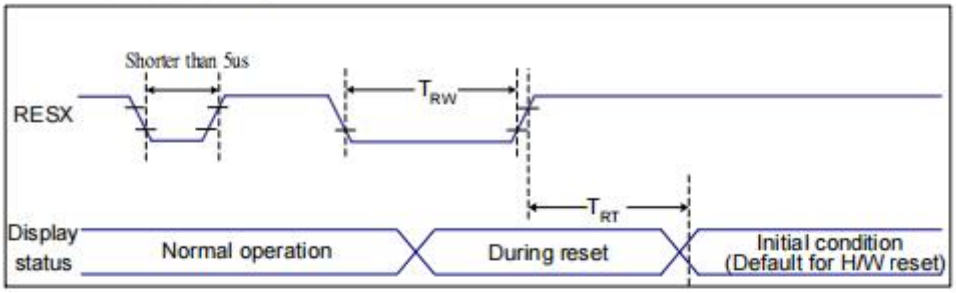


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Table 9 Reset Timing

Notes:

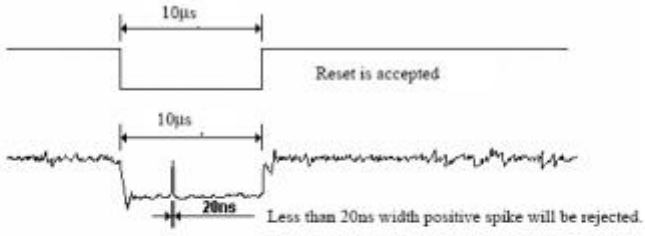
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

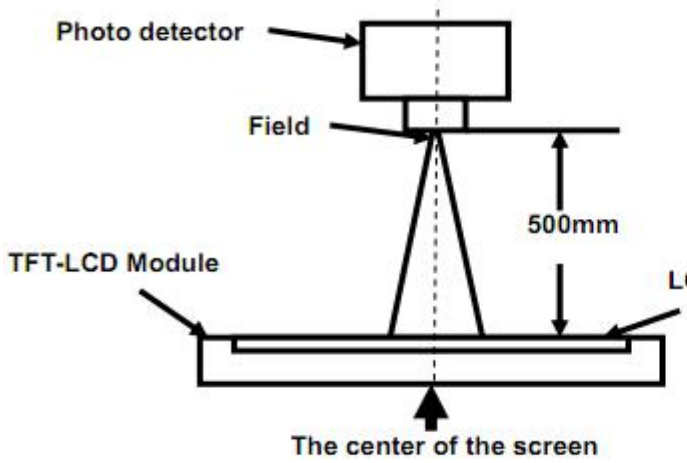
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

6. Optical Specifications

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Viewing Angle (CR≥10) B/L ON	θ_T	Φ=90°(12 o'clock)	80	-	-	deg	Note2
	θ_B	Φ=270°(6 o'clock)	80	-	-	deg	Note2
	θ_L	Φ=180°(9 o'clock)	80	-	-	deg	Note2
	θ_R	Φ=0°(3 o'clock)	80	-	-	deg	Note2
Response Time	T_{ON}	Normal θ=Φ=0°	-	15	17	msec	Note4
	T_{OFF}		-	15	17	msec	Note4
Contrast Ratio	CR		700	900	-	-	Note1 Note3
Color Chromaticity	W_X		0.250	0.300	0.350	-	Note1 Note5
	W_Y		0.276	0.326	0.376	-	Note1 Note5
Luminance	L		600	700	-	cd/m²	Note1 Note7
Luminance Uniformity	Y_U		75	80	-	%	Note1 Note6
NTSC	-		60	65	-	%	-

Note 1:Definition of optical measurement system

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Item	Photo detector	Field
Contrast Ratio	SR-3A	1°
Luminance		
Chromaticity		
Lum Uniformity		
Response Time	BM-7A	2°

Note 2:Definition of viewing angle range and measurement system
Viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).

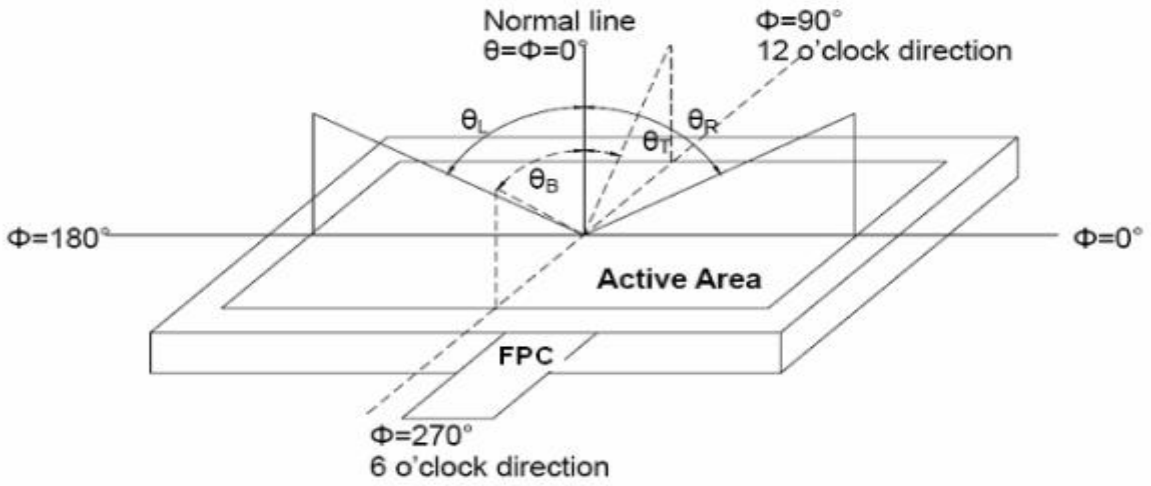


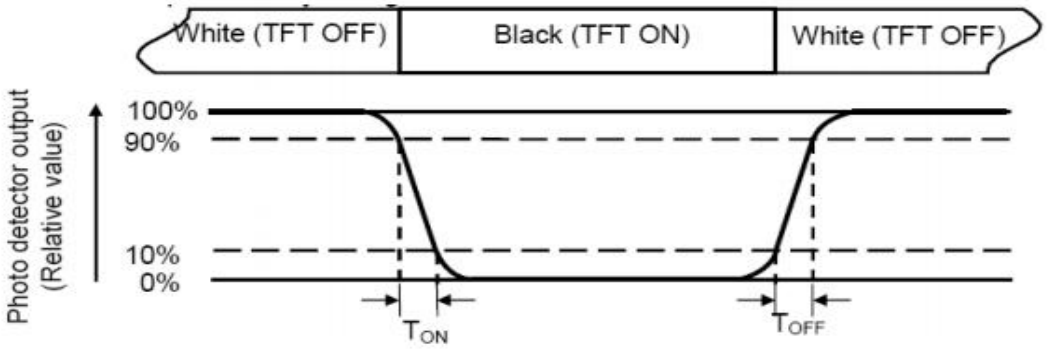
Fig. 1 Definition of viewing angle

Note 3: Definition of contrast ratio

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black”state. Rise time (TON) is the time between photo detector output intensity changed from 90% to 10%. And fall time (TOFF) is the time between photo detector output intensity changed from 10% to 90%.



Note 5:Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

Note 6:Definition of Luminance Uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.2.

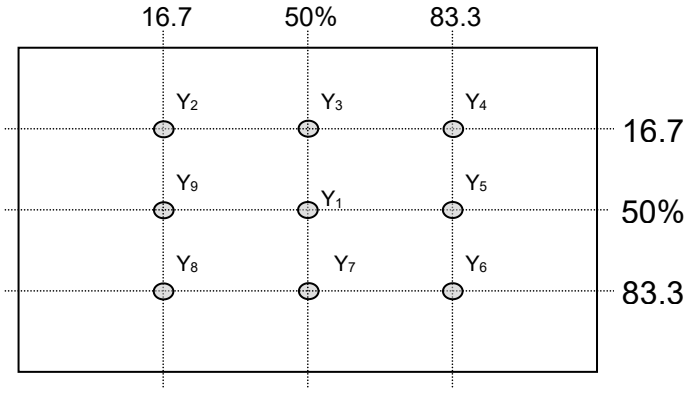


Fig. 2 Definition of points

Note 7:Definition of Luminance (Refer Fig. 2)

Surface luminance is the luminance with all pixels displaying white.

Lv = Average Surface Luminance with all white pixels(P1,P2,P3, ...,Pn).

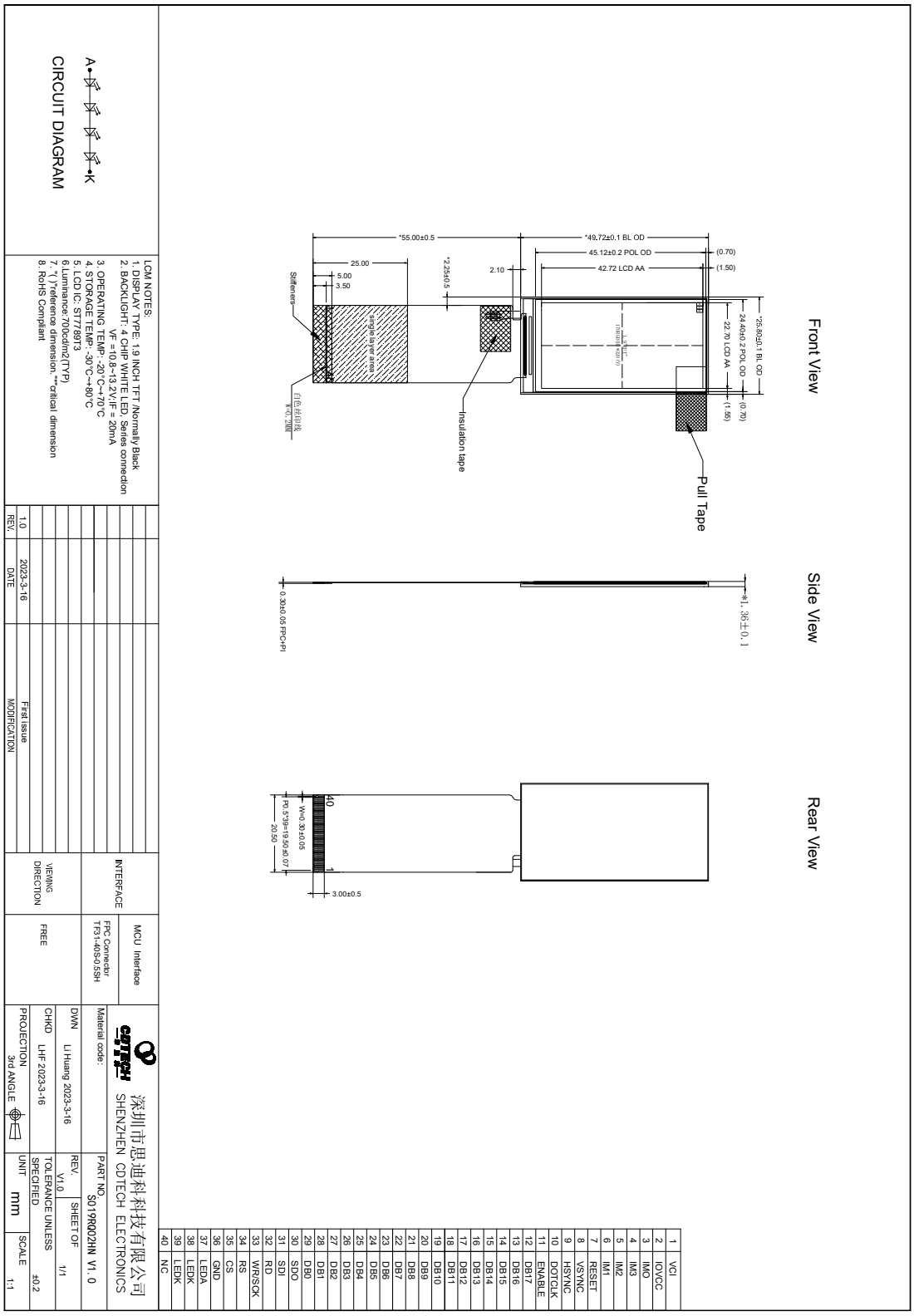
7. Reliability Test Items

Test Item	Test Conditions	
High Temperature Storage	Ta= +80℃	96hrs
Low Temperature Storage	Ta= -30℃	96hrs
High Temperature Operation	Ta= +70℃	96hrs
Low Temperature Operation	Ta= -20℃	96hrs
High Temperature and Humidity Storage	Ta= +60℃, 90% RH	96hrs
Thermal Shock (Non-operation)	-30℃/30 min ~ +80℃/30 min for 20 cycles Start with cold temperature end with high temperature	
Electro Static Discharge	Contact = ± 4 kV, class B Air = ± 8 kV, class B R=330Ω,C=150pF	
Vibration	Sweep: 10Hz~55Hz~10Hz Stroke: 1.5mm 2 hrs for each direction of X .Y. Z.	
Mechanical Shock	60G 6ms,±X,±Y,±Z 3 times for each direction	
Package Drop Test	Height: 60 cm 1 corner, 3 edges, 6 surfaces	

Notes: The test result shall be evaluated after the sample has been left at room temperature and humidity for 2 hours without load. No condensation shall be accepted. The sample will not be accepted if appear these defects:

1). Air bubble in the LCD
2). Seal leak or Glass crack
3). Non display or abnormal display
4). Brightness reduction >50%

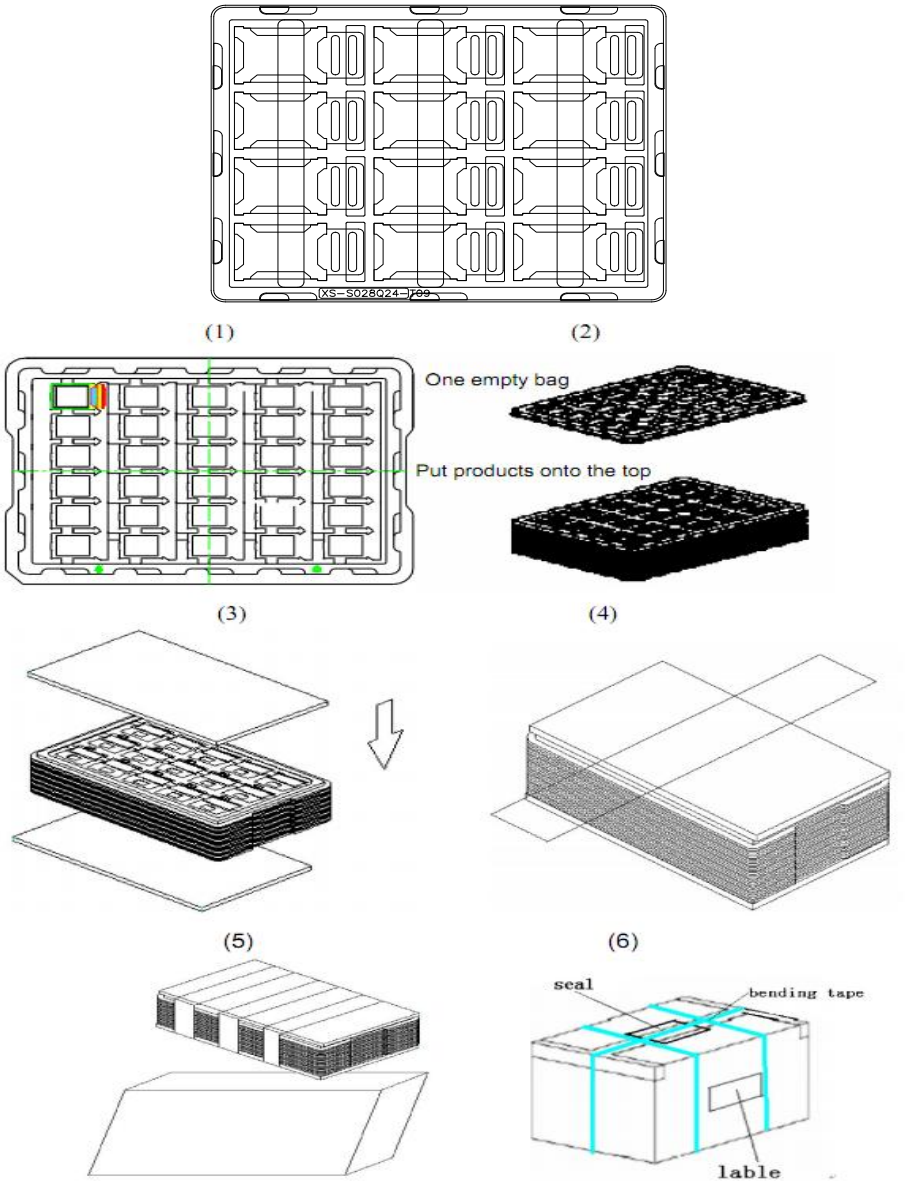
8. Mechanical Drawing



1	VCI	
2	IOVCC	
3	IM0	
4	IM3	
5	IM2	
6	IM1	
7	RESET	
8	VSYNC	
9	HSYNC	
10	DOTCLK	
11	ENABLE	
12	DB17	
13	DB16	
14	DB15	
15	DB14	
16	DB13	
17	DB12	
18	DB11	
19	DB10	
20	DB9	
21	DB8	
22	DB7	
23	DB6	
24	DB5	
25	DB4	
26	DB3	
27	DB2	
28	DB1	
29	DB0	
30	SDO	
31	SDI	
32	RD	
33	WR/SCK	
34	RS	
35	CS	
36	GND	
37	LEDA	
38	LEDK	
39	LEDK	
40	NC	

9. Packing

Packing Method



Steps:

1. Put module into tray cavity
2. Tray stacking
3. Put 1 cardboard under the tray stack and 1 cardboard above
4. Fix the cardboard to the tray stack with adhesive tape
5. Put the tray stack into carton
6. Carton sealing with adhesive tape

10. Precautions for Use of LCD modules

10.1 Handling Precautions

10.1.1. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.

10.1.2. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.

10.1.3. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

10.1.4. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

10.1.5. If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

- Isopropyl alcohol
- Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketene
- Aromatic solvents

10.1.6. Do not attempt to disassemble the LCD Module.

10.1.7. If the logic circuit power is off, do not apply the input signals.

10.1.8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

10.1.8.1. Be sure to ground the body when handling the LCD Modules.

10.1.8.2. Tools required for assembly, such as soldering irons, must be properly ground.

10.1.8.3. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

10.1.8.4. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

10.2 Storage Precautions

10.2.1.When storing the LCD modules,avoid exposure to direct sunlight or to the light of fluorescent lamps.

10.2.2.The LCD modules should be stored under the storage temperature range if the LCD modules will be stored for a long time,the recommend condition is :

Temperature : 0℃ ~40℃ Relatively humidity: ≤80%

10.2.3.The LCD modules should be stored in the room without acid, alkali and harmful gas.

10.3 Transportation Precautions

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.